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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kloster, et al.

Serial No.: 09/820,079

Filed: July 31, 2002

For: STRUCTURE IN A
MICROELECTRONIC DEVICE
INCLUDING A BI-LAYER FOR A
DIFFUSION BARRIER AND AN
ETCH STOP LAYER

Examiner: Thomas J. Magee

Group Art Unit: 2811

Attorney Docket No.: 42390.P11026

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231.

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AMENDMENT

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the July 31, 2002 Office Action, with the time for response having been
extended by one-month, please consider the following remarks: